| L | Hits | Search Text | DB | Time stamp |
|-------------|-------|--|-------------------|------------|
| Number 1 | 20031 | | | |
| 1 | 20031 | ptc or ntc or positive adj temperature | USPAT; | 2004/06/23 |
| | | adj coefficient or negative adj | US-PGPUB; | 13:52 |
| | | temperature adj coefficient | EPO; JPO; | |
| 2 | 1327 | thermally adj conductive adj adhesive | IBM_TDB | 2004/05/00 |
| 2 | 1527 | chermarry adj conductive adj adnesive | USPAT; | 2004/06/23 |
| | | | US-PGPUB; | 13:52 |
| | | | EPO; JPO; | |
| 3 | 0 | ((thermally adj conductive adj adhesive)) | IBM_TDB | 2004/06/02 |
|] | | with eloectrode | USPAT; | 2004/06/23 |
| | | with eloectiode | US-PGPUB; | 13:52 |
| | | | EPO; JPO; | |
| 4 | 0 | (thermally adj conductive adj adhesive) | IBM_TDB USPAT; | 2004/06/22 |
| • | | with eloectrode | l . | 2004/06/23 |
| | | with electione | US-PGPUB; | 13:53 |
| | | | EPO; JPO; | |
| 5 | 18 | (thermally adj conductive adj adhesive) | IBM_TDB USPAT; | 2004/06/23 |
| | | with electrode | US-PGPUB; | 13:53 |
| | | with ciccinde | EPO; JPO; | 13:55 |
| | | | IBM TDB | |
| 6 | 54444 | silicon adj carbide | USPAT; | 2004/06/23 |
| - | | DITTOM any outpide | US-PGPUB; | 13:54 |
| | | | EPO; JPO; | 13.34 |
| | | | IBM TDB | |
| 7 | 4 | ((thermally adj conductive adj adhesive) | USPAT; | 2004/06/23 |
| , | 1 | with electrode) and (silicon adj carbide) | US-PGPUB; | 14:00 |
| | | distribution and (billion adj calbide) | EPO; JPO; | 14.00 |
| | | | IBM TDB | |
| 8 | 454 | silicon with adhesive and silicon adj | USPAT; | 2004/06/23 |
| | 1 | carbide with adhesive | US-PGPUB; | 14:01 |
| | | The same of the sa | EPO; JPO; | 14.01 |
| | | | IBM TDB | 1 |
| 9 | 1 | (ptc or ntc or positive adj temperature | USPAT; | 2004/06/23 |
| | | adj coefficient or negative adj | US-PGPUB; | 14:02 |
| | | temperature adj coefficient) and | EPO; JPO; | 1 11102 |
| | | (((thermally adj conductive adj adhesive) | IBM TDB | [|
| | | with electrode) and (silicon adj | | |
| | | carbide)) and (silicon with adhesive and | | |
| 1 | | silicon adj carbide with adhesive) | |] |
| 12 | 1 | (ptc or ntc or positive adj temperature | USPAT; | 2004/06/23 |
| | | adj coefficient or negative adj | US-PGPUB; | 14:03 |
| | | temperature adj coefficient) and | EPO; JPO; | |
| | | (((thermally adj conductive adj adhesive) | IBM TDB | |
| | | with electrode) and (silicon adj | _ | |
| | | carbide)) | | |
| 13 | 1 | (((thermally adj conductive adj adhesive) | USPAT; | 2004/06/23 |
| | | with electrode) and (silicon adj | US-PGPUB; | 14:03 |
| | | carbide)) and (silicon with adhesive and | EPO; JPO; | |
| | | silicon adj carbide with adhesive) | IBM_TDB | |
| 10 | 8 | (ptc or ntc or positive adj temperature | USPAT; | 2004/06/23 |
| | | adj coefficient or negative adj | US-PGPUB; | 14:12 |
| | | temperature adj coefficient) and (silicon | EPO; JPO; | |
| | | with adhesive and silicon adj carbide | IBM_TDB | |
| | 10505 | with adhesive) | | |
| 14 | 19596 | (heater or heating adj element) with | USPAT; | 2004/06/23 |
| | | (electrode next adhesive) | US-PGPUB; | 14:13 |
| | | | EPO; JPO; | |
| 15 | 3.5 | A Objection on New Admin 2011 20 11 11 | IBM_TDB | |
| 15 | 16 | ,, | USPAT; | 2004/06/23 |
| | | (electrode next adhesive)) and (silicon | US-PGPUB; | 14:13 |
| | | with adhesive and silicon adj carbide | EPO; JPO; | |
| | | with adhesive) | IBM TDB | |